

Vishay Siliconix

P-Channel 1.8 V (G-S) MOSFET

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^d	Q _g (Typ.)		
	0.0155 at V _{GS} = - 4.5 V	- 13.4			
- 20	0.0195 at V _{GS} = - 2.5 V	- 12	36.5 nC		
	0.0250 at V _{GS} = - 1.8 V	- 10.5			

SO-8

Top View

S

FEATURES

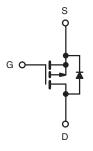
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R_g Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



ROHS COMPLIANT HALOGEN FREE

APPLICATIONS

- · Adaptor Switch
- High Current Load Switch
- Notebook



Ordering Information: Si4403CDY-T1-GE3 (Lead (Pb)-free and Halogen-free)

P-Channel MOSFET

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	- 20	V		
Gate-Source Voltage	V _{GS}	± 8			
	T _C = 25 °C		- 13.4		
Continuous Drain Current /T 150 °C)	T _C = 70 °C		- 10.7		
Continuous Drain Current (T _J = 150 °C)	T _A = 25 °C	I _D	- 9.4 ^{a, b}		
	T _A = 70 °C		- 7.5 ^{a, b}		
Pulsed Drain Current	I _{DM}	- 40	Α		
Continuous Course Dunin Diada Courset	T _C = 25 °C		- 4.1		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.1 ^{a, b}		
Avalanche Current	1 0.411	I _{AS}	- 15		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	11.25	mJ	
	T _C = 25 °C		5		
Manianus Davies Dissination	T _C = 70 °C		3.2	14/	
Maximum Power Dissipation	T _A = 25 °C	P _D	2.5 ^{a, b}	W	
	T _A = 70 °C		1.6 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	38	50	°C/W	
Maximum Junction-to-Foot	Steady State	R _{th IF}	20	25	C/VV	

Notes:

- a. Surface mounted on 1" x 1" FR4 board.
- b. t = 10 s.
- c. Maximum under steady state conditions is 85 $^{\circ}\text{C/W}.$
- d. Based on T_C = 25 °C.

Si4403CDY

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static						•	
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	/pc/T		- 14.5		m\//°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		2.8		mV/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$	- 0.4		- 1.0	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zara Cata Valtaga Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 70 \text{ °C}$			- 1	μΑ	
Zero Gate Voltage Drain Current					- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, V_{GS} = -5 \text{ V}$	- 20			Α	
	, ,	V _{GS} = - 4.5 V, I _D = - 9 A		0.0125	0.0155	0195 Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 6 A		0.0155	0.0195		
	- (- /	V _{GS} = - 1.8 V, I _D = - 3 A		0.0195	0.0250		
Forward Transconductance ^a g _{fs}		V _{DS} = - 10 V, I _D = - 9 A		40		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2380		pF	
Output Capacitance	C _{oss}	V _{DS} = - 10 V, V _{GS} = 0 V, f = 1 MHz		340			
Reverse Transfer Capacitance	C _{rss}			280			
Total Cata Chausa	Q _g	$V_{DS} = -10 \text{ V}, V_{GS} = -8 \text{ V}, I_{D} = -5 \text{ A}$		60	90		
Total Gate Charge				36.5	55	nC	
Gate-Source Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -5 \text{ A}$		3.1			
Gate-Drain Charge	Q _{gd}			9.9			
Gate Resistance	R _q	f = 1 MHz	1.0	4.8	9.6	Ω	
Turn-On Delay Time	t _{d(on)}			7	14		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_1 = 2 \Omega$		9	18	-	
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -8 \text{ V}, R_g = 1 \Omega$		108	200		
Fall Time	t _f	Ĭ		41	80		
Turn-On Delay Time	t _{d(on)}			14	28	ns	
Rise Time	t _r	$V_{DD} = -10 \text{ V, R}_{1} = 2 \Omega$		16	32		
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -5 \text{ A}, V_{GEN} = -4.5 \text{ V}, R_g = 1 \Omega$		101	200		
Fall Time	t _f			40	80		
Drain-Source Body Diode Characteris	stics					1	
Continous Source-Drain Diode Current I _S		T _C = 25 °C			- 4.1	Ι.	
Pulse Diode Forward Current	I _{SM}				- 40	A	
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.66	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}	3 - , - us		81	150	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	1		150	300	nC	
Reverse Recovery Fall Time	t _a	$I_F = -2.3 \text{ A, dI/dt} = 100 \text{ A/µs, T}_J = 25 ^{\circ}\text{C}$		43			
Reverse Recovery Rise Time	t _b			38		ns	

Notes:

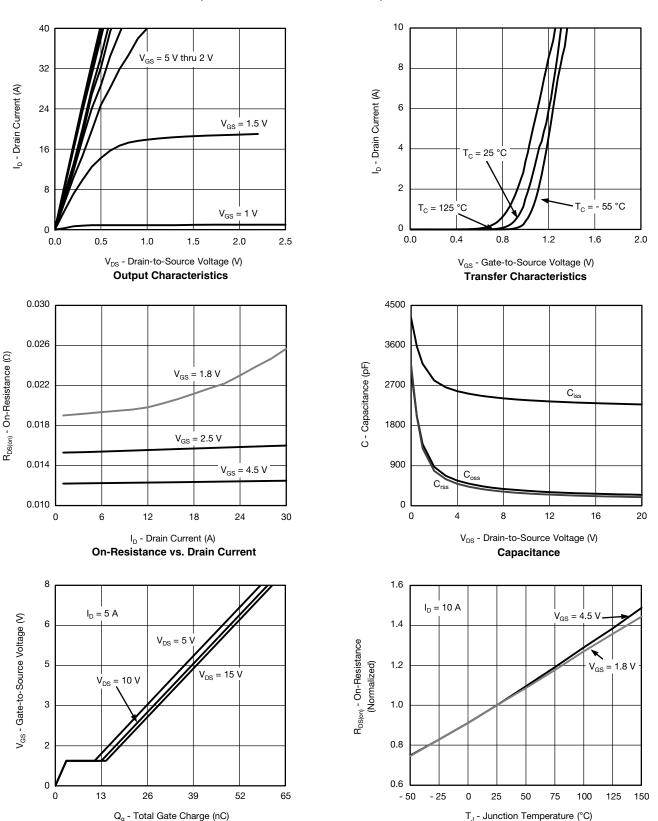
- a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Gate Charge

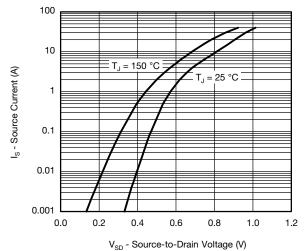
On-Resistance vs. Junction Temperature

Si4403CDY

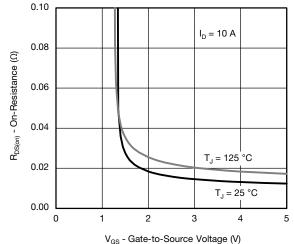
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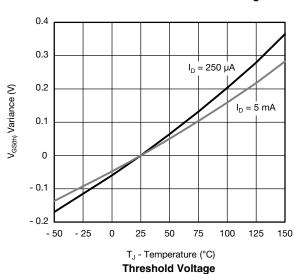
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

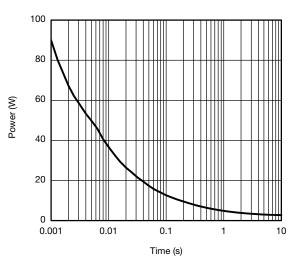


Source-Drain Diode Forward Voltage

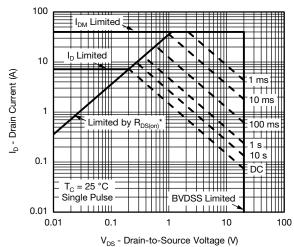


On-Resistance vs. Gate-to-Source Voltage





Single Pulse Power, Junction-to-Ambient



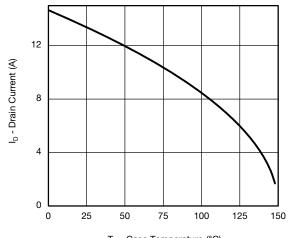
 * V_{GS} > minimum V_{GS} at which R_{DS(on)} is specified

Safe Operating Area

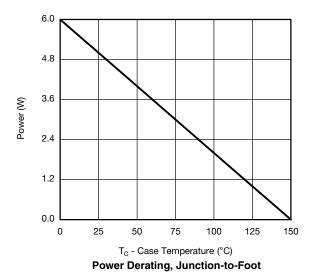


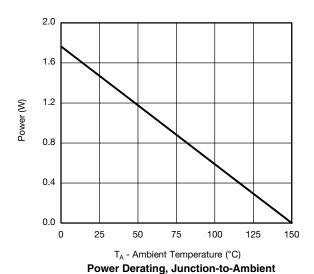
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



T_C - Case Temperature (°C) **Current Derating***





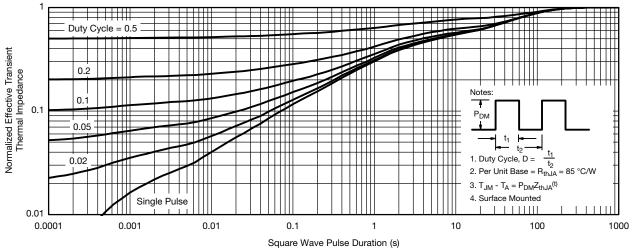
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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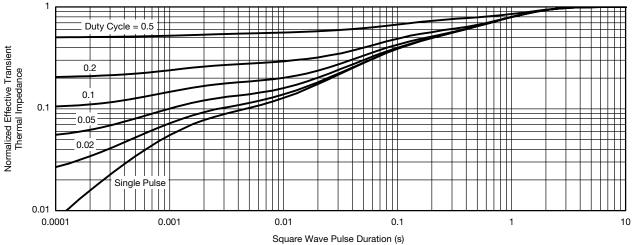
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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?67341.



SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012







	MILLIMETERS INCHES			HES		
DIM	Min	Max	Min	Max		
Α	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
Е	3.80	4.00	0.150	0.157		
е	1.27	BSC	0.050 BSC			
Н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I. 11-Sep-06						

DWG: 5498

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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